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FORM PT0-1984 U.S. DEPARTMENT OF COMMERCE RECORDATION FORM COVER SHEET PATENTS ONLY KIT-003 Patent and Trademark Office To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof. 1. Name of conveying party(ies) 2. Name and address of receiving party(ies) 04/03/01 1) Hiroyasu OSHIMA Name: Kanazawa Institute of Technology 2) Yutaka KOMENO 3) Tutomu YAMAZAKI Internal Address: 4) Masaaki TAKASE 5) Hiroyuki YOSHIDA 6) Takashi SAIE 7) Yuuji TANIGUCHI Additional name(s) of conveying party(ies) attached No Street Address: 7-1, Ohgigaoka Nonoichimachi, Ishikawa-gun 3. Nature of conveyance: City: Ishikawa-ken, JAPAN □ Merger **☒** Assignment Additional name(s) & address(es) attached ☐ Yes ☒ No ☐ Security Agreement ☐ Change of Name Other Execution Date: 1), 3) & 5) March 3, 2001; 2) March 21, 2001; 6) & 7) March 23, 2001; and 4) March 26, 2001 4. Application number(s) or patent number(s): 29 If the document is being filed together with a new application, the execution date of the application is March 3, 2001, March 21, 2001, March 23, 2001 & March 26, 2001 Additional numbers attached No 6. Total number of applications and patents involved:..... 1 5. Name and address of party to whom correspondence concerning document should be mailed: 7. Total fee (37 CFR 3.41).....\$ 40.00 Name: RADER, FISHMAN & GRAUER Enclosed Internal Address: Suite 501 Authorized to be charged to Deposit Account 1233 20th Street, NW 8. Deposit account number: 18-0013 Street Address: (Attach duplicate copy of this page if paying by deposit account) Zip: 20036 City: Washington, D.C. DO NOT USE THIS SPACE 9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original April 3, 2001

Eugene G. Byrd, Reg. No. 47,361

Name of Person Signing

PATENT REEL: 011702 FRAME: 0319

Date

Total number of pages comprising cover sheet 1

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

ELECTRIC CART

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Kanazawa Institute of Technology, a Japanese Institute with offices at 7-1, Ohgigaoka, Nonoichimachi, Ishikawa-gun, Ishikawa-ken, JAPAN, (hereinafter referenced as ASSIGNEES) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of Ten Dollar (\$10.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEES, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEES, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEES or its designee, as ASSIGNEES or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of

	insert the serial number and filing he spaces that follow: Serial te:
This assignment exe	cuted on the dates indicated below.
Hiroyasu OSHIMA	
Name of first inventor	Execution date of U.S. Patent Application
Ishikawa, JAPAN	
Residence of first inventor	
大島 弘在	March 3, 2001.
Signature of first inventor	Date of this assignment
Yutaka KOMENO	
Name of second inventor	Execution date of U.S. Patent Application
Ishikawa, JAPAN	
Residence of second inventor	

Signature of second inventor

PATENT REEL: 011702 FRAME: 0321

Date of this assignment

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEES will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

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Name of first inventor	Execution date of U.S. Patent Application
Ishikawa, JAPAN Residence of first inwentor	
Signature of first inventor	Date of this assignment
Yutaka KOMENO Name of second inventor	Execution date of U.S. Patent Application
name of second inventor	Execution date of 0.5. Fatent Application

Residence of second inventor

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Signature of second inventor

Date of this assignment

March 21 2001

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Signature of seventh inventor	Date of this assignment

RECORDED: 04/03/2001